



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

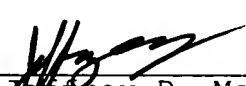
APPLICANT: OH ET AL. DOCKET NO.: WK2K1070  
SERIAL NO: 10/015,374 EXAMINER: WILLIAMS  
FILED: 12/12/2001 ART UNIT: 2826  
TITLE: STACKING STRUCTURE OF SEMICONDUCTOR CHIPS AND  
SEMICONDUCTOR PACKAGE USING IT.

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Weiss & Moy, P.C.  
4204 North Brown Avenue  
Scottsdale, Arizona 85251-3989

August 26, 2002

I hereby certify that on the 26th day of August, 2002, this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

  
Jeffrey D. Moy

Dear Sir:

AMENDMENT LETTER

This is in response to the Office Action dated July 24, 2002 in regards to the above identified patent application. Please amend the subject patent application as follows:

09/19/2002 RSMITH 00000006 230830 10015374  
01 FC:102 84.00 CH